CLAIMS

1. An apparatus, comprising:

a chamber body and a lid defining a process volume therein;

a substrate support disposed in the process volume;

a first electrode embedded in the substrate support;

a radio frequency (RF) source coupled to the first electrode;

an impedance matching circuit disposed between the RF source and the first electrode;

a second electrode embedded in the substrate support;

a power source coupled to the second electrode; and

an electrode filter disposed between and coupled to the second electrode and the power source,

wherein the electrode filter comprises:

a first inductor coupled to the second electrode;

a second inductor in series with the first inductor;

a third inductor in series with the first inductor and the second inductor;

a resistor in series with the first inductor, the second inductor, and the third inductor, the resistor coupled to the power source;

a first capacitor in parallel with the second inductor;

a first ground path coupled to the electrode filter between the second inductor and the third inductor, the first ground path comprising a second capacitor; and

a second ground path coupled to the electrode filter between the third inductor and the resistor, the second ground path comprising a third capacitor.

2. The apparatus of claim 1, wherein the second electrode comprises a conductive mesh.

3. The apparatus of claim 1, further comprising:

a gas distribution plate coupled to the chamber body and disposed opposite the substrate support.

4. The apparatus of claim 3, wherein the second electrode is disposed between the first electrode and a surface of the substrate support facing the gas distribution plate.